

## CALL FOR PAPERS

# Special Issue of the IEEE Transactions on Dielectrics and Electrical Insulation on Electrets and Related Phenomena

We are pleased to announce that the **June 2022** issue of the *IEEE Transactions on Dielectrics and Electrical Insulation* (TDEI) will be a special issue on electrets and related phenomena. This issue is open to **all** authors. Presenters of papers at the IEEE 18<sup>th</sup> International Symposium on Electrets (ISE18) to be held during September 24–28, 2021 in Shanghai (China) are especially encouraged to submit their work to this special issue. For more information on ISE18 please go to <https://ise18.tongji.edu.cn/>.

Topics include, but are not limited to:

- Charge-related phenomena in dielectrics
- Dielectric and space-charge relaxations
- Dielectrics in high electric fields
- Dielectric relaxation spectroscopy
- Energy storage in dielectrics and ionic materials
- Thermally stimulated phenomena
- Electrets for energy harvesting
- Piezo-, pyro- and ferroelectrets
- Electrocaloric and pyroelectric materials
- Piezo-electric phenomena in polymers and organics/biomaterials
- Applications of organic and polymer based piezoelectric materials
- Electrets and functional polymers in organic electronics
- Optical effects, photoelectrets
- Electrostatic and dielectric phenomena in life sciences – bioelectrets and biomedical applications
- Soft transducers and electro-electrets (dielectric elastomers)
- Nanoscale electrostatic, dielectric and electret materials
- Electret and dielectric phenomena in nanoscale structures
- Applications of electrets in low-frequency communication
- Applications of electrets in air purification

Authors are invited to submit their papers to the Guest Editors of the Special Issue no later than **October 15, 2021**, at the TDEI website (<http://www.cloznet.com/ieeetdei>). On the submission form there is a location for Special Issue paper submission where the name of the Guest Editor can be chosen. Instructions for the preparation of manuscripts and a template are available at the website or directly from here: <http://www.cloznet.com/ieeetdei/TDEI%20Submissions%20Template%202021.dotx>.

In accordance with IEEE policy, papers that have been published in any conference proceedings cannot be republished. A plagiarism tool will be used to verify originality. Therefore, authors of the ISE18 proceedings are strongly advised to **significantly** expand and enhance their conference paper versions prior to submission to this Special Issue of the IEEE *TDEI*.

Further questions concerning this Special Issue can be directed to either one of the three Guest Editors or directly to the Editor-in-Chief of the *IEEE Transaction on Dielectrics and Electrical Insulation* Professor Michael Wübbenhorst ([wubbenhorst@kuleuven.be](mailto:wubbenhorst@kuleuven.be)). The Guest Editors for this special issue are:

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